Title (en)
A SUBSTRATE HOLDER FOR HOLDING A CONDUCTIVE SUBSTRATE DURING PLATING THEREOF

Title (de)
SUBSTRATHALTER ZUM HALTEN EINES LEITFÄHIGEN SUBSTRATS WÄHREND DES GALVANISIERENS

Title (fr)
PORTE-SUBSTRAT POUR MAINTENIR UN SUBSTRAT CONDUCTEUR PENDANT LE PLACAGE DE CELUI-CI

Publication
**EP 2350357 A1 20110803 (EN)**

Application
**EP 08875022 A 20081114**

Priority
EP 2008009658 W 20081114

Abstract (en)
[origin: WO2010054677A1] A system for plating a conductive substrate is provided. The system comprises a conductive substrate, comprising a first and a second conductive side, wherein said first side of the conductive substrate is to be plated. Furthermore, the system comprises a substrate holder with an attachment means, for attaching the conductive substrate to the substrate holder, such that a first surface of the substrate holder faces the second side of the conductive substrate. The substrate holder also comprises a resilient contact means, attached to the first surface of the substrate holder, said resilient contact means being connectable to a first external potential. The second side of the conductive substrate is provided with an insulating material exposing the second side of the conductive substrate, such that at least one contact area is provided, wherein the resilient contact means is in contact with the exposed second side in said at least one contact area. A substrate holder therefore is also provided.

IPC 8 full level
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CPC (source: EP KR US)
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Citation (search report)
See references of WO 2010054677A1

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